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2014	7	250.2000	1	50.0000
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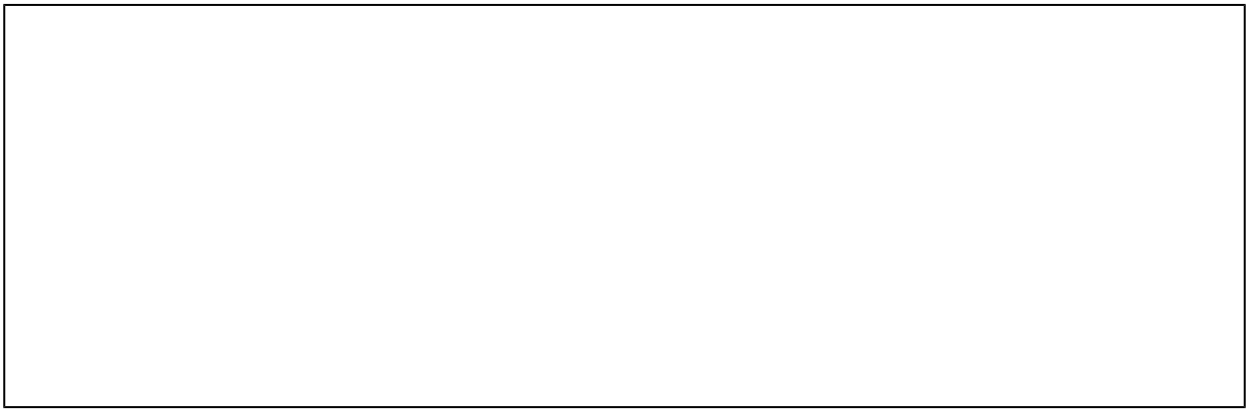

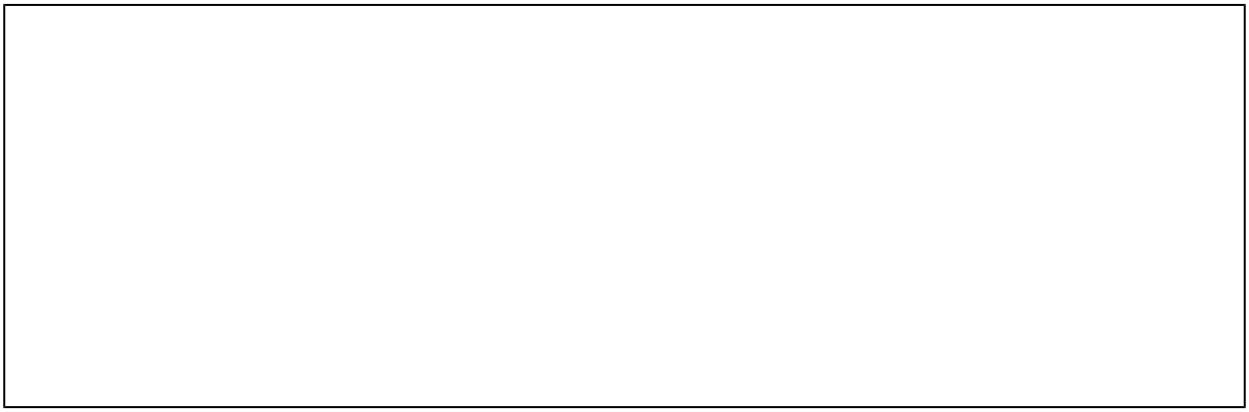

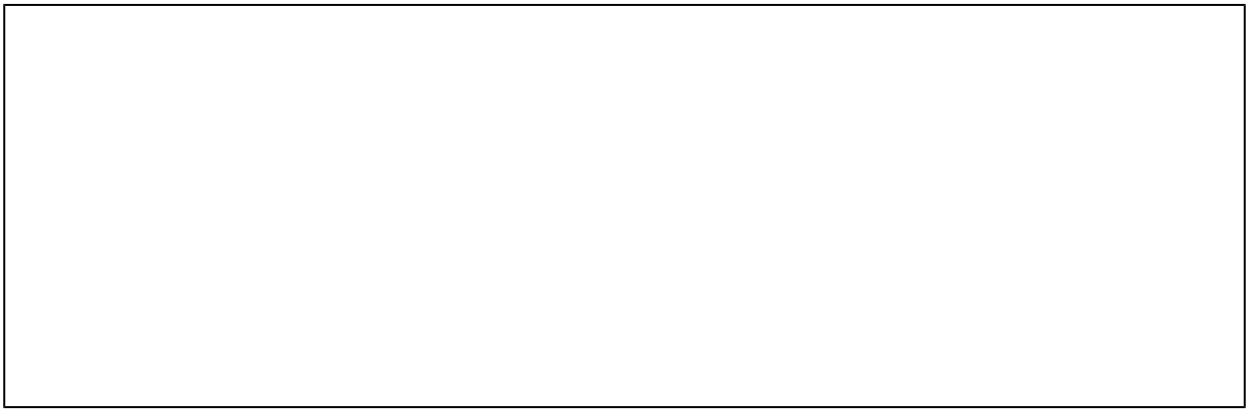

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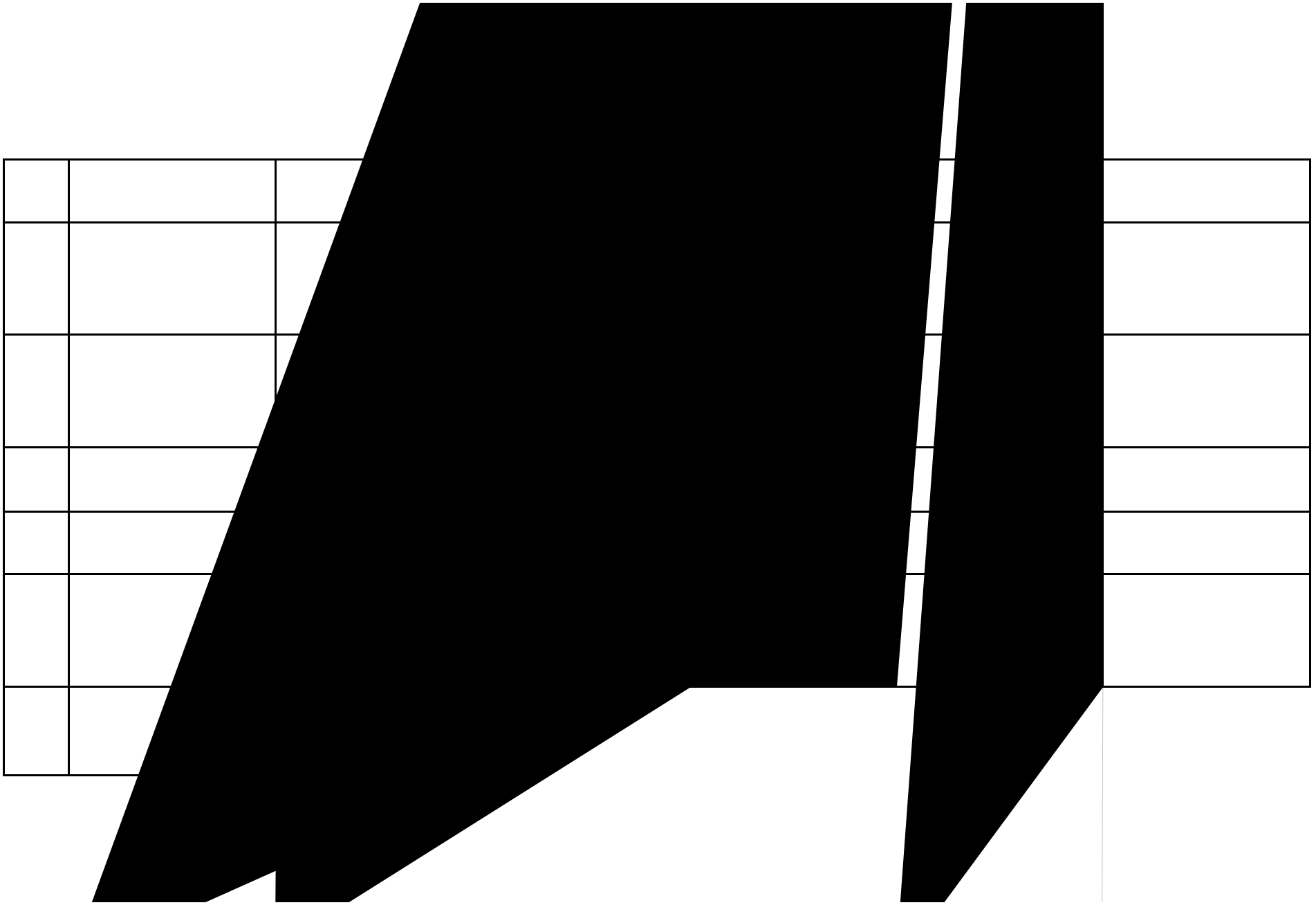

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9	Volterra ADC		2014	6.0000		A
10	XXX XXX		2014	135.0000		A
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1	Low capacitance and highly reliable blind through-silicon-vias (TSVs) with vacuum-assisted spin coating of polyimide dielectric liners	Yan, Yangyang ;XIONG Miao; LIU Bin ;Ding,Yingtao CHEN ZhiMing	2016	SCIENCE CHINA-TECHNOLOGICAL SCIENCES		1.4
2	Modeling and Analysis of Vertical Noise Coupling in TSV-Based 3D Mixed-Signal Integration	Shiwei Wang;Yingtao Ding; Zhiming Chen;Huanyu He;Jian-Qiang Lu	2016	Microelectronic Engineering		1.3
3	Wideband Capacitance Evaluation of Silicon—Insulator—Silicon Through-Silicon-Vias for 3D Integration Applications	Xinghua Wang;Miao Xiong;Zhiming Chen;Bohao Li;Yangyang Yan;Ding,Yingtao	2016	IEEE ELECTRON DEVICE LETTERS		2.5
4	Highly conformal polyimide liner deposition in high-aspect-ratio through-silicon-vias (TSVs)	Yingtao Ding; Yangyang Yan; Miao Xiong; Shiwei Wang ;Qianwen Chen;Zhiming Chen	2016	Micro & Nano Letters		0.7

5	Study of Vacuum-Assisted Spin Coating of Polymer Liner for High-Aspect-Ratio Through-Silicon-Via Applications	sY. Yan ;Ding,Yingtao	2016	IEEE TRANSACTIONS ON COMPONENTS		1.2
6	Innovative polyimide liner deposition method for high-aspect-ratio and high-density through-silicon-vias (TSVs)	Ding,Yingtao; Miao Xiong;Yangyang Yan;Shiwei Wang;Qianwen Chen;Weijing Wang	2016	Microelectronic Engineering		1.3
7	A Truly Balanced Q-Band CMOS Frequency Doubler Based on Hybrid Quadrature Coupler	?Jiayue Wan?;??Zhiming Chen?;??Qiang An?;??Xinghua Wang	2016	IEEE Microwave and Wireless Components Letters		1.6
8	An analytical model for capacitance of silicon-insulator-silicon through-silicon-vias	Bohao Li ; An'an Li ; Miao Xiong ; Jianxun Yang ; Zhiming Chen ; Yingtao Ding	2016	Miao Xiong ; Jianxun Yang ; Zhiming Chen ; Yingtao Ding		0.8
9	DOA?Estimation?With?Enhanced?DOFs by Exploiting Cyclostationarity	Liu, Jianyan Lu, Yilong Zhang, Yanmei Wang, Weijiang	2016	IEEE TRANSACTIONS ON SIGNAL PROCESSING		2.6
10	An accurate power and temperature simulation framework for Network-on-Chip	Jianxun Yang?;??Shan Cao	2016	?Integrated Circuits and Microsystems (ICICM)		

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1		ZL201310280690.6		2016			
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5	XXX XXX	ZL 201318003936.6		2015			
6	XX	ZL 201318003694.0		2015			
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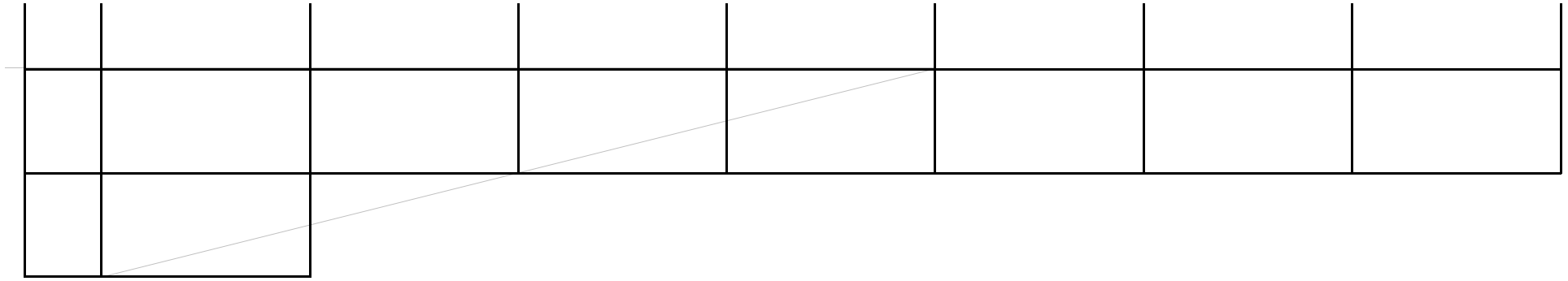

21	XXXX				2014		30.0
22			63999		2014		150.0
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24	RCS				2015		120.0
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27					2015		75.0
28	RF mems				2015		10.0
29	SOC				2015		300.0
30					2015		30.0
31	VGA/DVI				2015		54.4

32					2015		128.5
33					2015		83.8
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35	XX				2015		400.0
36	L XX				2015		10.0
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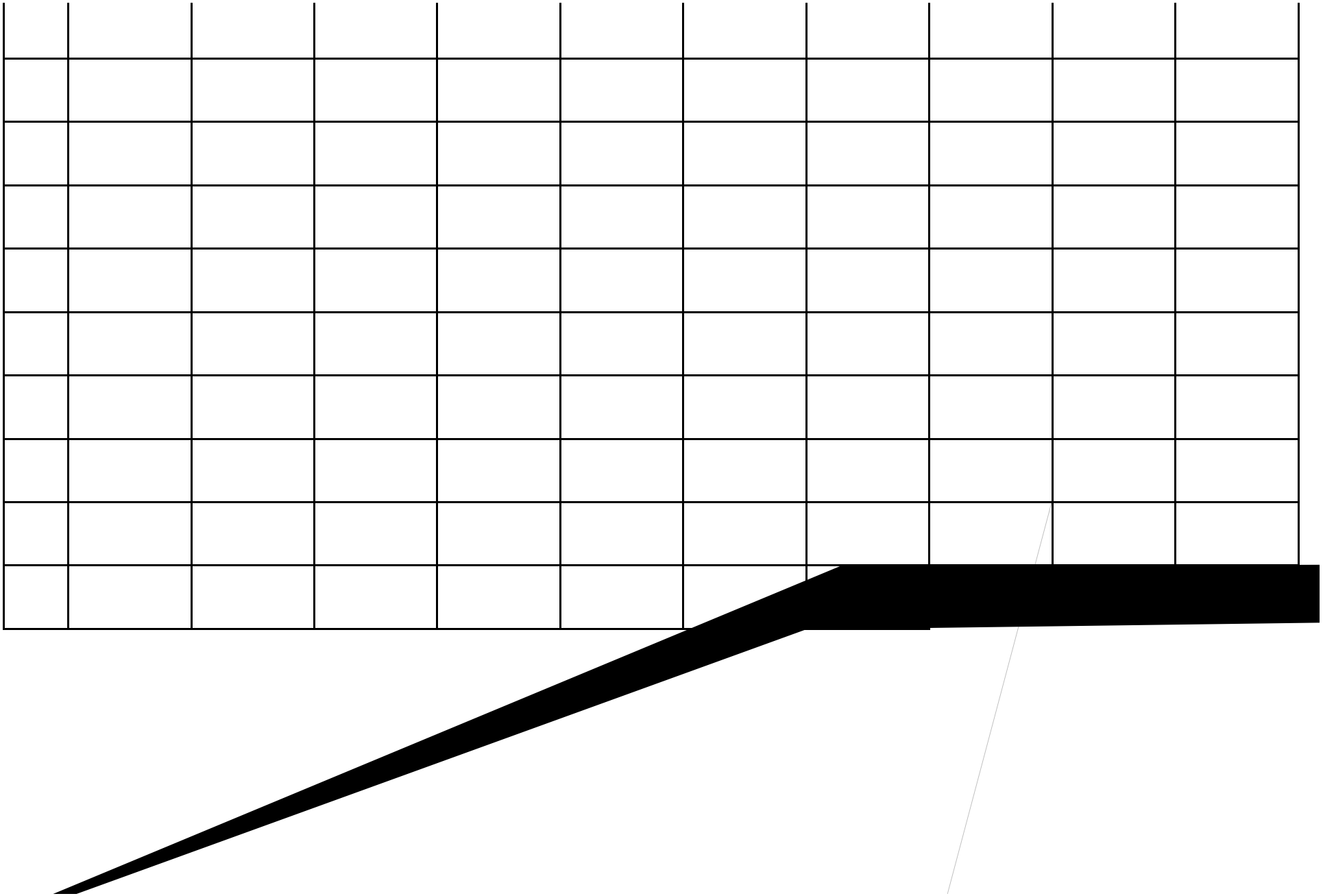

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